

# Paul Paret

## List of Publications by Year in descending order

Source: <https://exaly.com/author-pdf/10665344/publications.pdf>

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2258059

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2272923

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citing authors

#	ARTICLE	IF	CITATIONS
1	Reliability and Lifetime Prediction Model of Sintered Silver Under High-Temperature Cycling. IEEE Journal of Emerging and Selected Topics in Power Electronics, 2022, 10, 5181-5191.	5.4	7
2	Thermal and Mechanical Design of a High-Voltage Power Electronics Package. , 2021, , .		1
3	Packaging of an 8-kV Silicon Carbide Diode Module with Double-Side Cooling and Sintered-Silver Joints. , 2021, , .		9
4	Parametric Design Study of a Power Electronics Package for Improving Solder Joint Reliability. , 2020, , .		1
5	Liquid-Cooled Aluminum Silicon Carbide Heat Sinks for Reliable Power Electronics Packages. Journal of Electronic Packaging, Transactions of the ASME, 2019, 141, .	1.8	9
6	Electrothermal Modeling and Analysis of Gallium Oxide Power Switching Devices. , 2019, , .		2
7	Mechanical Characterization Study of Sintered Silver Pastes Bonded in a Double-Lap Configuration. , 2018, , .		2
8	Transient Liquid Phase Bonding of AlN to AlSiC for Durable Power Electronic Packages. Advanced Engineering Materials, 2018, 20, 1800039.	3.5	16
9	Thermomechanical Modeling of Sintered Silver – A Fracture Mechanics-Based Approach. Additional Conferences (Device Packaging HiTEC HiTEN & CICMT), 2017, 2017, 1-15.	0.2	1
10	Reliability of Bonded Interfaces for Automotive Power Electronics. , 2013, , .		9